

ABSTRACT

Provided are an electroplating device and a substrate cleaning method related to the technical field of semiconductor equipment. The electroplating device comprises: a chuck, configured to hold a substrate in a horizontal position; a drive unit, configured to drive the chuck to rotate; a nozzle, configured to spray a cleaning solution to clean the substrate held by the chuck; wherein, the coverage area of the cleaning solution sprayed by the nozzle onto the substrate includes a co-rotation zone and a counter-rotation zone, and the co-rotation zone is larger than the counter-rotation zone; the co-rotation zone is a zone where the cleaning solution sprayed by the nozzle has a velocity component in the rotation direction of the substrate; the counter-rotation zone is a zone where the cleaning solution sprayed by the nozzle has a velocity component against the rotation direction of the substrate. In the electroplating device and the substrate cleaning method of the present invention, the position of the nozzle is strategically set such that more of the cleaning solution sprayed from the nozzle falls into the co-rotation region. In this way, the cleaning solution can be better flung into a water shield, thereby preventing a large volume of the cleaning solution from falling into a cathode chamber and diluting the cathode electroplating solution, which can otherwise affect the stability of the electroplating solution.